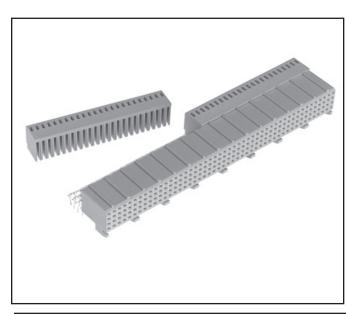
3M[™] MetPak[™] 2-FB Socket

2 mm 4/5-Row, Solder Tail or Press-Fit With Tail Cover, Right Angle

MP2 Series



- End-to-end stackable
- · Offset dual-beam contact minimizes insertion force
- Expanded pin counts
- Protective Push-Cap
- Monoblockable
- Press or heat stake peg
- 12 mm modular units
- Meets global IEC 61076-4-104 Futurebus+® standard
- See the Regulatory Information Appendix (RIA) in the "RoHS compliance" section of www.3Mconnector.com for compliance information (RIAE1 & C1 apply)

Date Modified: May12, 2010

TS-1115-C Sheet 1 of 4

Physical

Insulation:

Material: High Temp LCP Flammability: UL 94V-0

Color: Beige

Contact:

Material: Copper Alloy

Plating:

Underplating: 50 μ" (1.27 μm) Nickel Wiping Area: See Ordering Information Solder Tails: See Ordering Information

Electrical

Current Rating: Signal: 1.5 A - All contacts simultaneously

Insulation Resistance: $10^3 M\Omega$ Withstanding Voltage: 1,000 V_{AC}

Environmental

Temperature Rating: -55° C to 125° C

Process Temperature Rating: 260°C (Profile per J-STD-020C)

Moisture Sensitivity Level: 1 (per J-STD-020C)

MetPak is a trademark of 3M Company.

Futurebus+ is a registered trademark of the Institute of Electrical and Electronic Engineers, Inc. (IEEE)

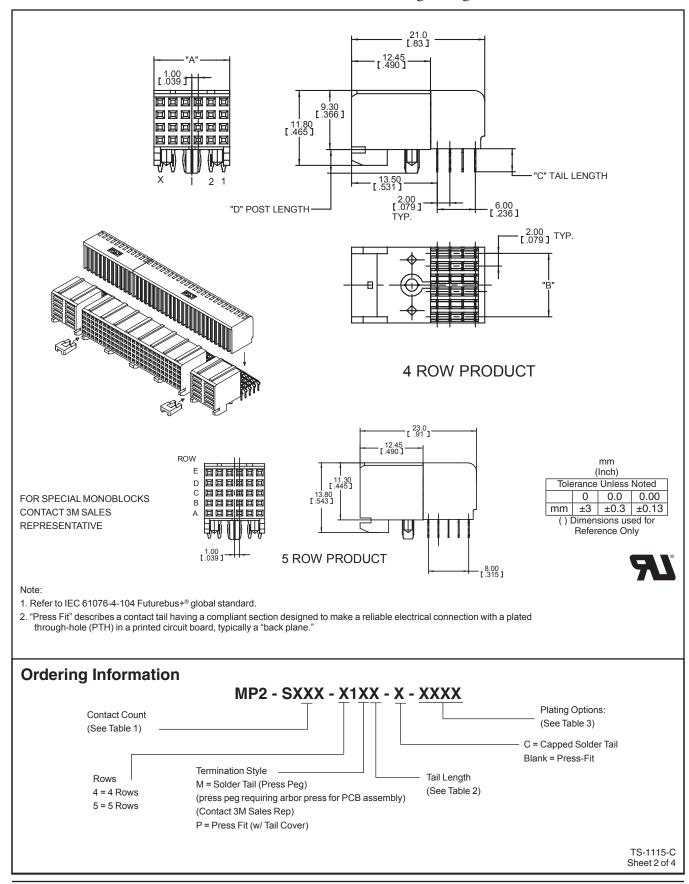
3M

Electronic Solutions Division Interconnect Solutions http://www.3Mconnector.com

UL File No.: E68080

3M is a trademark of 3M Company. For technical, sales or ordering information call 800-225-5373

2 mm 4/5-Row, Solder Tail or Press-Fit With Tail Cover, Right Angle



3M

2 mm 4/5-Row, Solder Tail or Press-Fit With Tail Cover, Right Angle

Table 1 - Connector & Row Lengths							
Pin Count	Dim "A" mm (Inch)		Dim "B" mm (Inch)		Rows	Block Count	
024	11.95	[0.471]	10.00	[0.394]	4	1	
048	23.95	[0.943]	22.00	[0.866]	4	2	
072	35.95	[1.415]	34.00	[1.339]	4	3	
096	47.95	[1.889]	46.00	[1.811]	4	4	
120	59.95	[2.36]	58.00	[2.283]	4	5	
144	71.95	[2.833]	70.00	[2.756]	4	6	
168	83.95	[3.305]	82.00	[3.228]	4	7	
192	95.95	[3.778]	94.00	[3.701]	4	8	
030	11.95	[0.471]	10.00	[0.394]	5	1	
060	23.95	[0.943]	22.00	[0.866]	5	2	
090	35.95	[1.415]	34.00	[1.339]	5	3	
120	47.95	[1.888]	46.00	[1.811]	5	4	
150	59.95	[2.361]	58.00	[2.283]	5	5	
180	71.95	[2.833]	70.00	[2.756]	5	6	
210	83.95	[3.305]	82.00	[3.228]	5	7	
240	95.95	[3.778]	94.00	[3.701]	5	8	

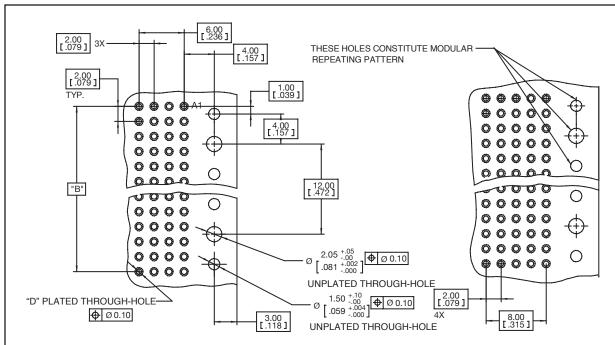
Table 2 - Tail & Post Lengths				
Contact-to-PC Board Tail Termina- tion Option No.		Dim "C"	Dim. "D"	
Solder	Press-Fit*			
M1		2.72 [0.107]	3.57 [0.141]	
M2	P1	3.53 [0.139]	3.57 [0.141]	

^{*}Compliant-Pin Tail

Table 3 - Plating						
Plating Suffix	Press-Fit Tails*	Solder Tails	Plating Composition			
TG30	(RIA E2 & C2 apply)	(RIA E3 & C2 apply)	8 & C2 apply) 0.76 μm [30 μ"] Min. Au Contact Area 2.54 μm [100 μ"] Min. SnPb Tail Area 1.27 μm [50 μ"] Min. Ni all over			
TR30	(RIA E2 & C2 apply)	(RIA E3 & C2 apply)	0.08 μm [3 μ"] Min. Au Contact Area 0.67 μm [27 μ"] Min. PdNi Contact Area 2.54 μm [100 μ"] Min. SnPb Tail Area 1.27 μm [50 μ"] Min. Ni all over			
FJ	(RIA E1 & C1 apply)	(RIA E1 & C1 apply)	0.25 μm [10 μ"] Min. Au Contact Area 2.54 μm [100 μ"] Min. Matt Whisker Mitigating Sn Tail Area 1.27 μm [50 μ"] Min. Ni all over			
KR	(RIA E1 & C1 apply)	(RIA E1 & C1 apply)	0.76 μm [30 μ"] Min. Au Contact Area 2.54 μm [100 μ"] Min. Matt Whisker Mitigating Sn Tail Area 1.27 μm [50 μ"] Min. Ni all over			
LR	(RIA E1 & C1 apply)	(RIA E1 & C1 apply)	0.08 μm [3 μ"] Min. Au Contact Area 0.67 μm [27 μ"] Min. PdNi Contact Area 2.54 μm [100 μ"] Min. Matt Whisker Mitigating Sn Tail Area 1.27 μm [50 μ"] Min. Ni all over			

^{*}Compliant-Pin Tail

TS-1115-C Sheet 3 of 4 2 mm 4/5-Row, Solder Tail or Press-Fit With Tail Cover, Right Angle



RECOMMENDED 4 ROW PCB HOLE MOUNTING PATTERN

RECOMMENDED 5 ROW PCB HOLE MOUNTING PATTERN

Table 4 HOLE PLATING For TG30 and TR30 FINISHES ONLY					
HOLE	Finished Dia. mm [in]	Cu Thickness mm [in]	SnPb Thickness microns [µ"]	Drilled Hole Dia. mm [in]	
"D"	0.65-0.80 [.02560315]	0.025 [.001] min	15 [600] max	0.81-0.86 [.03190339]	

	Table 5 HOLE PLATING For KR and LR FINISHES ONLY						
Н	IOLE	Finished Dia. mm [in]	Cu Thickness mm [in]	Immersion Matte Sn Thickness microns [μ"]	Electrolitic Au Thickness microns [µ"]	OSP ENTEK Thickness microns [µ"]	Drilled Hole Dia. mm [in]
	"D"	0.700-0.800 [.02760315]	0.025-0.045 [0.001-0.002]	0.5 - 2.5 [20 - 100]	0.1 - 0.5 [4 - 20]	0.2 - 0.5 [8 - 20]	0.830-0.860 [.03300340] or 0.85mm [#66] TWIST DRILL

TS-1115-C Sheet 4 of 4

Important Notice

All statements, technical information, and recommendations related to 3M's products are based on information believed to be reliable, but the accuracy or completeness is not guaranteed. Before using this product, you must evaluate it and determine if it is suitable for your intended application. You assume all risks and liability associated with such use. Any statements related to the product which are not contained in 3M's current publications, or any contrary statements contained on your purchase order shall have no force or effect unless expressly agreed upon, in writing, by an authorized officer of 3M.

Warranty; Limited Remedy; Limited Liability.

This product will be free from defects in material and manufacture for a period of ninety (90) days from the time of purchase. 3M MAKES NO OTHER WARRANTIES INCLUDING, BUT NOT LIMITED TO, ANY IMPLIED WARRANTY OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE. If this product is defective within the warranty period stated above, your exclusive remedy shall be, at 3M's option, to replace or repair the 3M product or refund the purchase price of the 3M product. Except where prohibited by law, 3M will not be liable for any indirect, special, incidental or consequential loss or damage arising from this 3M product, regardless of the legal theory asserted.



3M Electronics Solutions Division

6801 River Place Blvd. Austin, TX 78726-9000 U.S.A. 1-800-225-5373 www.3Mconnector.com

Please recycle. Printed in USA. © 3M 2010. All rights reserved. RIA-2217B-E

3M is a trademark of 3M Company.